Docket No.

241280US2S DIV

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Tsutomu SATO et al.

SERIAL NO: 1

New Application

GAU:

FILED:

Herewith

**EXAMINER:** 

FOR:

SEMICONDUCTOR DEVICE FORMED IN SEMICONDUCTOR LAYER ARRANGED ON SUBSTRATE WITH

ONE OF INSULATING FILM AND CAVITY INTERPOSED BETWEEN THE SUBSTRATE AND THE

SEMICONDUCTOR LAYER

# INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR

Applicant(s) wish to disclose the following information.

### REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449 that were cited in the parent application Serial No. 10/091,448, filed March 7, 2002. Copies of the listed references were filed in the parent application.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

### **RELATED CASES**

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

### **CERTIFICATION**

- ☐ Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- □ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

## **DEPOSIT ACCOUNT**

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment form is enclosed herewith, or credit any overpayment to deposit account number <u>15-0030</u>. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER-& NEUSTADT, P.C.

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Eckhard H. Kuesters

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Form PTO 1449	U.S. DEPARTMENT OF COMMERCE			ATTY DOCKET NO.		SERIAL NO.		
(Modified)		PATENT AND TRAI	DEMARK OFFICE	241280US2S DIV		New Application		
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT				
				Tsutomu SATO et al.				
				FILING DATE		GROUP		
				Herewith				
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
	AA	6,380,037 B1	04/2002	Osanai, Jun				
	AB	6,288,427 B2	09/2001	Huang, Feng-Yi				
	AC	6,229,179 B1	05/2001	Song et al.				
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	AN							
FOREIGN PATENT DOCUMENTS								
	DOCUMENT DATE COUNTRY					TRANSLATION		
		NUMBER	DATE	COUNTRY		YES NO		
	AO	11-17001	01/22/99	Japan		*	X	
	AP							
	AQ							
	AR							
	AS							
	AT							
	AU							
	AV							
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)								
	AW Robert HANNON, et al., "0.25" m Merged Bulk DRAM and SOI Logic Using Patterned SOI", 2000 Symposium on VLSI, TECHNOLOGY DIGEST OF TECHNICAL PAPERS, (2 pages)							
	AX	H.L. HO, et al., "A 0.13µm High-Performance SOI Logic Technology with Embedded DRAM for System-On-A-Chip Application", 2001 IEDM TECHNICAL DIGEST, (4 pages)						
	AY							
	AZ	Additional References sheet(s) a					rences sheet(s) attached	
Examiner					Date Considered			
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								